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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR ATTORNEY DOCKET		CONFIRMATION NO.
10/709,428	05/05/2004	Cheng-Yen Huang	Cheng-Yen Huang FTCP0035USA	
	7590 01/08/200 RICA INTELLECTUA	EXAMINER		
P.O. BOX 506	XIA 00116	TRINH, HOA B		
MERRIFIELD, VA 22116			ART UNIT	PAPER NUMBER
		2814		
SHORTENED STATUTOR	Y PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE	
3 MO	NTHS	01/08/2007	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

		App	lication No.	ation No. Applicant(s)				
		10/	709,428	HUANG, CHENG	-YEN			
Office Action Summary			miner	Art Unit				
		Vikk	i H. Trinh	2814				
Period fo	The MAILING DATE of this communic r Reply	ation appears	on the cover sheet	with the correspondence a	ddress			
WHIC - Exter after - If NC - Failu Any	ORTENED STATUTORY PERIOD FO CHEVER IS LONGER, FROM THE MA Issions of time may be available under the provisions of SIX (6) MONTHS from the mailing date of this commu- period for reply is specified above, the maximum state re to reply within the set or extended period for reply we eply received by the Office later than three months afted patent term adjustment. See 37 CFR 1.704(b).	ALING DATE (f 37 CFR 1.136(a). I nication. utory period will apply rill, by statute, cause	OF THIS COMMUI n no event, however, may y and will expire SIX (6) M the application to become	NICATION. a reply be timely filed ONTHS from the mailing date of this of ABANDONED (35 U.S.C. § 133).				
Status			•					
1)⊠	Responsive to communication(s) filed	Lon 27 Octobe	r 2006					
•	•	b)∐ This actio	-					
′=	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is							
٠,۵	closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.							
Dispositi	on of Claims	•	• •					
4\I⊠	Claim(s) 11 19 and 33-36 is/are pend	ing in the appl	ication					
	 ✓ Claim(s) 11,19 and 33-36 is/are pending in the application. 4a) Of the above claim(s) is/are withdrawn from consideration. 							
	Claim(s) is/are allowed.							
•	Claim(s) <u>11,19 and 33-36</u> is/are reject	ted.						
7)	Claim(s) is/are objected to.							
8)	Claim(s) are subject to restrict	ion and/or elec	tion requirement.					
Applicati	on Papers							
	The specification is objected to by the	Examiner.						
. ——			or b) objected	to by the Examiner.				
,	10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner. Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
	Replacement drawing sheet(s) including				CFR 1.121(d).			
11)	The oath or declaration is objected to	by the Examin	er. Note the attacl	ned Office Action or form P	TO-152.			
Priority (ınder 35 U.S.C. § 119		•		•			
•	_	or foreign prior	ity under 35 U.S.C	: 8 119(a)-(d) or (f)				
	12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of:							
-,	1. Certified copies of the priority documents have been received.							
	Certified copies of the priority documents have been received in Application No							
	3. Copies of the certified copies of the priority documents have been received in this National Stage							
	application from the Internation	al Bureau (PC	T Rule 17.2(a)).					
* 5	See the attached detailed Office action	for a list of the	e certified copies r	ot received.				
					•			
Attachmen	t(s)							
	e of References Cited (PTO-892)			w Summary (PTO-413)				
3) 🔲 Infor	e of Draftsperson's Patent Drawing Review (PT mation Disclosure Statement(s) (PTO-1449 or F			No(s)/Mail Date of Informal Patent Application (P1	ГО-152)			
rape	r No(s)/Mail Date		o) La Other.	 ·				

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

 (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 2. Claims 11, 19, and 33-36 are rejected under 35 U.S.C. 102(e) as being anticipated by Sutardja et al. (6,903,448) (hereinafter Sutardja).

As to claim 11, 35, Sutardja discloses a packaging comprising a package substrate 1 (figure 7) connected inherently to either a high voltage or a low voltage for turning the device on, a chip 2 (fig. 7) mounted on the package substrate and comprises a plurality of bonding option unit (col. 5, lines 47-48) that comprises a bonding pad (col. 5, lines 47-48); a plurality of first lead frame 72, 52 (fig. 7; the bonding pad has corresponding first lead frame 52, 72 (fig. 7) such that there exists a one-to-one correspondence between the bonding pads and the first lead frames; the first lead frame 52, 72 being connected to either a high voltage or a low voltage (note Vout), wherein the voltage level of the first lead frame 52, 72 is inherently logical opposite of the voltage level of the substrate; wherein the bonding pad (col. 5, lines 47-48) of each bonding option unit is connected to

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the package substrate 1 or the corresponding first lead frame 52, 72 for providing two types of bonding options for each bonding option unit (fig. 7).

As to claim 19, Sutardja discloses a method of packaging comprising the steps of providing a package substrate 1 (fig. 7) and connecting inherently to either a high voltage or a low voltage, mounting a chip 2 (fig. 7) on the package substrate 1 and comprising a plurality of bonding option unit (Col. 5, lines 47-48) that comprises a bonding pad; providing a plurality of first lead frame 52,72 (fig. 7) such that there exists a one-to-one correspondence between the bonding pads and the first lead frames; connecting the bonding pad to the substrate 1 or the corresponding first lead frame 52, 72 (fig. 7); the first lead frame 52, 72 (fig. 7) being connected inherently to either a high voltage or a low voltage (note Vout), wherein the voltage level of the first lead frame 52, 72 is inherently logical opposite of the voltage level of the substrate 1 (GND); wherein each bonding pad is selectively connected to the package substrate 1 or the first lead frame 52, 72 (fig. 7) for providing two types of bonding options for each bonding option unit (fig. 7).

As to claims 33 and 34,36, Sutardja further teaches the device and method of providing a plurality of second lead frames 51, 73 (fig. 7), each bonding pad (col. 5, lines 47-48; fig. 7) of the chip 2 (fig. 7) having a corresponding second lead frame 51, 73, wherein the second lead frames 51, 73 are used for inputting signals to the corresponding bonding pad (fig. 7), and each bonding pad (fig. 7) is connected to the substrate 1, the corresponding first lead frame 52, 752 or the corresponding second lead frame 51, 73 (fig. 7) for providing three types of bonding options for each bonding option unit (fig. 7)

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such that there exists a one-to-one correspondence between the bonding pads and the first lead frames.

Response to Arguments

3. Applicant's arguments with respect to claims 11, 19, and 33-34 have been considered but they are not persuasive.

Claims 11, 19, 33-34 fail to overcome Sutardja, because Sutardja teaches all of the limitation of the claims. In particular, the newly amended phrase "such that there exists a one-to-one correspondence between the bonding pads and the first lead frames" merely reiterates the functionality of the bonding pads relative to the leadframes. Applicants even admit on page 6, lines 20, that Surtadja discloses numerous bonding pads and numerous lead frames that can easily accommodate at least some one-to-one correspondence between the bonding pads and the lead frames. Thus, Surtadja still read on the present invention.

Conclusion

4. THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event,

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however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any request for information regarding to the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Also, status information for published applications may be obtained from either Private PAIR or Public Pair. In addition, status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. If you have questions pertaining to the Private PAIR system, please contact the Electronic Business Center (EBC) at 866-217-9197 (toll free).

Lastly, paper copies of cited U.S. patents and U.S. patent application publications will cease to be mailed to applicants with Office actions as of June 2004. Paper copies of foreign patents and non-patent literature will continue to be included with office actions. These cited U.S. patents and patent application publications are available for download via the Office's PAIR. As an alternate source, all U.S. patents and patent application publications are available on the USPTO web site (www.uspto.gov), from the Office of Public Records and from commercial sources. Applicants are referred to the Electronic Business Center (EBC) at http://www.uspto.gov/ebc/index.html or 1-866-217-9197 for information on this policy. Requests to restart a period for response due to a missing U.S. patent or patent application publications will not be granted.

Vikki Trinh, Patent Examiner AU 2814

> HOWARD WEISS PRIMARY EXAMINER